

**S aled h lder for semic nductor wafer etching**

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**Abstract**

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The holder has a cast elastic body (1) with concentric circular lips (2,3) between which electrical contact leaf springs (14-17) are provided and a channel section (6) opens from the end of a vacuum line (4). A relatively large hole (7) through the body is closed by a disc (8) snapped into a groove (9). At the high temperature of etching, pressure is built up in the space (11) between the disc and the wafer. To avoid consequential damage to the wafer a relief duct (12) is provided at atmospheric pressure.

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